

ABSTRACT OF THE DISCLOSURE

A manufacturing method for a COF semiconductor device according to the present invention comprises:

5 Step (A) of applying an insulating resin composition to a surface of an insulating tape on the surface of which a plurality of wiring patterns is arranged;

 Step (B) of pressably contacting a semiconductor element to the wiring patterns in the condition wherein the insulating resin
10 composition is not yet cured; and

 Step (C) of fixing the semiconductor element to the wiring patterns so as to be electrically connected by curing the insulating resin composition, wherein

 the manufacturing method for a COF semiconductor device
15 further includes Step (D) of pre-heating the insulating tape from the rear surface side before, during, and/or after the application of the insulating resin composition.